RoodMicrotec
powerful solutions

RoodMicrotec Newsletter

11

November 2010 • RoodMicrotec

Industrial activity is increasing

After my trip to the US in March of this year I concluded that any rising demand was still tentative. Over the past month I have again visited many customers in the US, and I am now very confident that industrial activity there has increased and will continue to increase. In fact, this increased activity is a global phenomenon, which is reflected in our Engineering business unit order portfolio.

While the activity in this sector lagged behind in the first half of this year due to orders being postponed, we are now seeing a clear rise, which we anticipate will continue into 2011.

Other pleasing news is that we have successfully completed audits by two of our customers. This will result in a further expansion of our activities for these customers and therefore of sales, both this year and next year.

Also, as you may have read in our press release of 29 September, we have found a new CFO. Mr Remy Cuny will join us on 1 November.

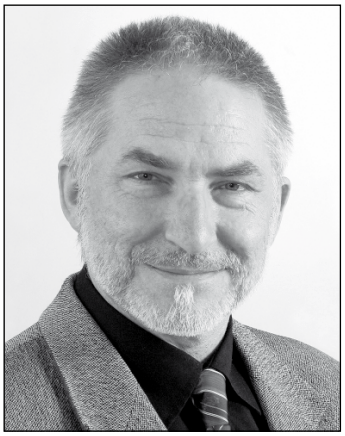
Monitored burn-in: a clear competitive advantage

Klaus Dittmann, Qualification & Reliability Investigation manager at RoodMicrotec, explains that burn-in testing approximates, in a compressed timeframe, the electrical and thermal conditions to which the device would be subjected during its normal life.

Burn-in tests subject devices to various input stimuli at temperatures generally ranging between 85°C and 150°C and at elevated voltages.

'With increasing complexity of electronic devices the requirements for burn-in systems are being raised. In some cases this can result in shifting functionality from the system onto the burn-in burn boards adding active circuitries. With conventional controlled systems it is not possible to map a fail during a 6-48h stress phase.

This gap can be closed with monitoring burn-in systems. RoodMicrotec has invested strategically in this area to deliver added valued to the customer. Systems of this kind are able to recognise and identify failing devices early on in their operational life (so called infant mortality). Measurements during the stress phase can be used to monitor the state of the device under stress conditions. Furthermore, intelligent procedures of integrated testing between stress periods can help to reduce the burn-in time and thus achieve significant costs savings. Higher reliability, reduced overall costs at a higher throughput are strong arguments for using monitoring burn-in. RoodMicrotec is the only independent test solution provider in Europe delivering that service. This is a key issue in the current market situation and provides a clear competitive advantage for the customer.'



Supply chain management: first-class one-stop-shopping

'In 2003 we received a first request from the market to support a customer from project start to the final end-product,' says Hans-Peter Neuber, [COO / Authorized Officer] at RoodMicrotec. 'Already back in 2004, we could offer our customers comprehensive services ranging from wafer test to final test. Today we perform full supply chain management for the total lifecycle of ASICs and optoelectronic devices. We cooperate with certified suppliers and keep direct contact with foundries and assembly houses in Europe and Asia. Having started with approx. 150k assembly parts, we now handle some 7-10 million parts per year.'

'Our services are of interest especially for the growing number of fabless companies. These tend to be smaller companies requesting volumes which assembly houses consider as too low or for which the unit price would be too high. As we have a high number of customers, we sometimes can even leverage volumes towards assembly houses, resulting in better pricing.

Our credo is: we start where the foundry services end, from monitoring wafer level product quality to packaged components down to full logistics handling. In the area of wafer level this includes for example design support for testability, test program development, adaptation of test software, wafer logistics (ordering, monitoring, storage), inspection and packaging. For packaged components we develop test programs, adapt test software, offer qualification according to industry standards or customer-specified flows, and of course we do final tests. Once the product is ready to be shipped we take care of the worldwide shipment to end-customers. Another important logistics service is building up safety stocks of approx. 10%. We work with rolling forecasts to ensure sufficient safety stock throughout the year.

In addition, we offer a comprehensive range of services such as characterisation, screening, chip repair (FIB), qualification and handling of field returns.

The picture below shows our supply chain management service portfolio.

Please note that customers are not obliged to buy the entire package of services; individual elements or bundles can also be ordered.

We see excellent opportunities for sustained growth with our current services.
In future, we plan to extend our technical services by e.g. offering package selection consultancy.'

Agenda

electronica 2010 is coming!
RoodMicrotec is exhibiting at the electronica 2010 in Munich which takes place from November 9 till November 12, 2010.
You are invited to visit RoodMicrotec at booth A5.179 in hall 5.

Investor relations: Philip Nijenhuis, investor-relations@roodmicrotec.com
Irmgard Bayerle, irmgard.bayerle@roodmicrotec.com
Sales and marketing: Reinhard Pusch, reinhard.pusch@roodmicrotec.com
Editor in chief: Marlies Kort, Kort Investor Relations
Design and Layout: SjeWorks, V. Vogelaar
Images: S. Jellema, SjeWorks; RoodMicrotec

RoodMicrotec N.V.
"Rembrandt"
Dokter van Deenweg 58
NL-8025 BC Zwolle
The Netherlands
Telephone +31 (0) 38 4215 216

RoodMicrotec Stuttgart GmbH
Motorstraße 49
D-70499 Stuttgart
Telephone: +49 (0) 711 86709-0

RoodMicrotec Nördlingen GmbH+Co. KG
Oettinger Strasse 6
D-86720 Nördlingen
Telephone +49 (0) 9081 804-0